Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

2SK2866

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) = 0.54Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 9.0 S$ (typ.) • Low leakage current : $I_{DSS} = 100 \mu A$ (max) ($V_{DS} = 600 V$)

• Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

| Characteri | stics | Symbol | Rating | Unit | |
|--|------------------------|------------------|---------|------|--|
| Drain-source voltage | | V_{DSS} | 600 | V | |
| Drain-gate voltage (R | _{GS} = 20 kΩ) | V_{DGR} | 600 | V | |
| Gate-source voltage | | V _{GSS} | ±30 | V | |
| Drain current | DC (Note 1) | I _D | 10 | Α | |
| Diain current | Pulse (Note 1) | I _{DP} | 40 | Α | |
| Drain power dissipatio | n (Tc = 25°C) | P_{D} | 125 | W | |
| Single pulse avalanche energy (Note 2) | | E _{AS} | 363 | mJ | |
| Avalanche current | | I _{AR} | 10 | Α | |
| Repetitive avalanche energy (Note 3) | | E _{AR} | 12.5 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature range | | T _{stg} | -55~150 | °C | |

10.3MAX. 93.6±0.2

1.6MAX. 1.6

Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|--|------------------------|------|------|
| Thermal resistance, channel to case | R _{th (ch-c)} | 1.0 | °C/W |
| Thermal resistance, channel to ambient | R _{th (ch-a)} | 83.3 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 6.36 mH, R_{G} = 25 Ω , I_{AR} = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



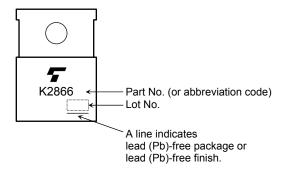
Electrical Characteristics (Ta = 25°C)

| Charac | cteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--------------------------------------|-----------------|----------------------|--|-----|------|------|------|
| Gate leakage cu | rrent | I _{GSS} | V _{GS} = ±25 V, V _{DS} = 0 V | _ | _ | ±10 | μΑ |
| Gate-source bre | eakdown voltage | V (BR) GSS | I _G = ±10 μA, V _{DS} = 0 V | ±30 | _ | _ | V |
| Drain cut-off cur | rrent | I _{DSS} | V _{DS} = 600 V, V _{GS} = 0 V | | _ | 100 | μΑ |
| Drain-source br | eakdown voltage | V (BR) DSS | I _D = 10 mA, V _{GS} = 0 V | 600 | _ | _ | V |
| Gate threshold v | oltage | V _{th} | V _{DS} = 10 V, I _D = 1 mA | 2.0 | _ | 4.0 | V |
| Drain-source Ol | N resistance | R _{DS} (ON) | V _{GS} = 10 V, I _D = 5 A | | 0.54 | 0.75 | Ω |
| Forward transfer | admittance | Y _{fs} | V _{DS} = 10 V, I _D = 5 A | 3.0 | 9.0 | _ | S |
| Input capacitano | е | C _{iss} | | | 2040 | _ | |
| Reverse transfer capacitance | | C _{rss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | - | 210 | _ | pF |
| Output capacitance | | Coss | | - | 630 | _ | |
| Switching time | Rise time | t _r | $V_{GS} = 10V \qquad I_{D} = 5A \qquad V_{OUT}$ $R_{L} = 40\Omega$ $V_{DD} = 200V$ | _ | 22 | _ | - ns |
| | Turn-on time | t _{on} | | _ | 58 | _ | |
| | Fall time | t _f | | 1 | 36 | | |
| | Turn-off time | t _{off} | Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$ | | 190 | _ | |
| Total gate charg plus gate-drain) | e (gate-source | Qg | | | 45 | | |
| Gate-source charge | | Q _{gs} | $V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$ | | 25 | | nC |
| Gate-drain ("miller") Charge | | Q _{gd} | | | 20 | _ | |

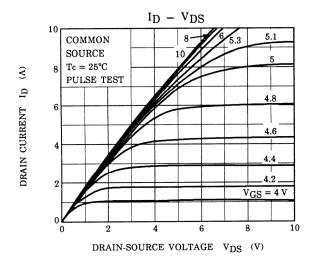
Source-Drain Ratings and Characteristics (Ta = 25°C)

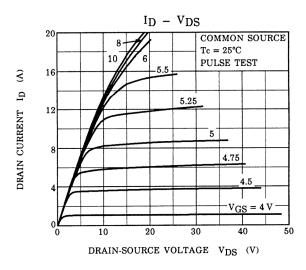
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|---|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I _{DR} | _ | _ | _ | 10 | Α |
| Pulse drain reverse current (Note 1) | I _{DRP} | _ | _ | _ | 40 | Α |
| Forward voltage (diode) | V _{DSF} | I _{DR} = 10 A, V _{GS} = 0 V | _ | _ | -1.7 | V |
| Reverse recovery time | t _{rr} | I _{DR} = 10 A, V _{GS} = 0 V | 1 | 1300 | 1 | ns |
| Reverse recovery charge | Q _{rr} | dl _{DR} / dt = 100 A / μs | _ | 16 | _ | μC |

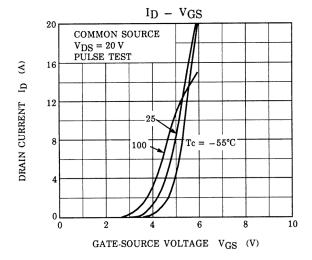
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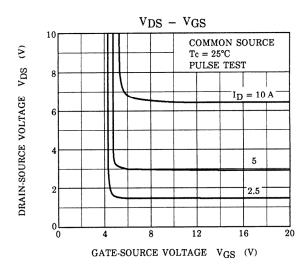


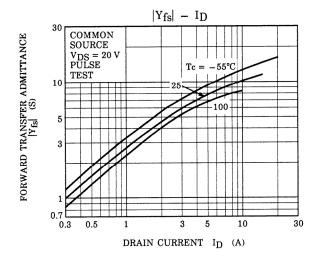
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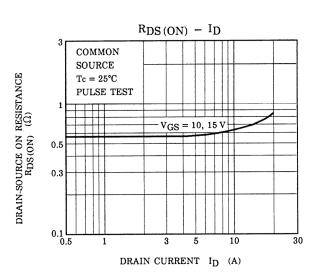




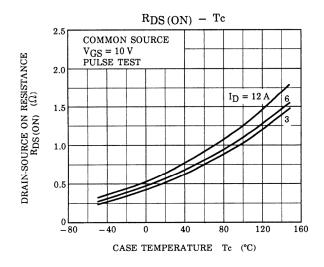


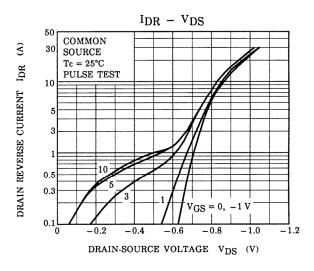


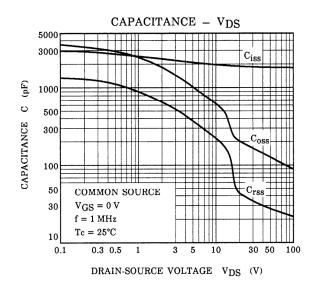


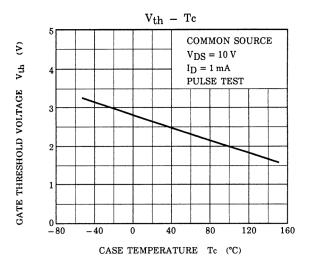


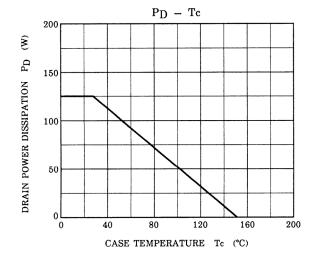
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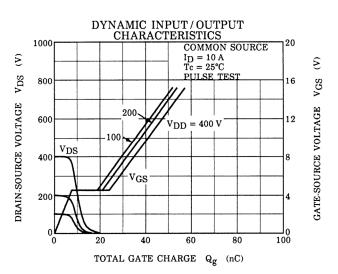


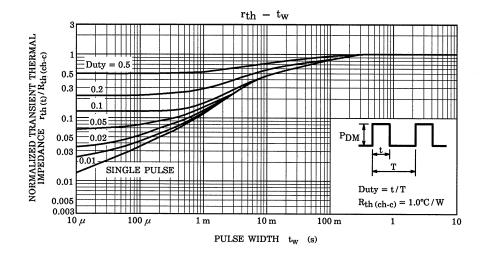


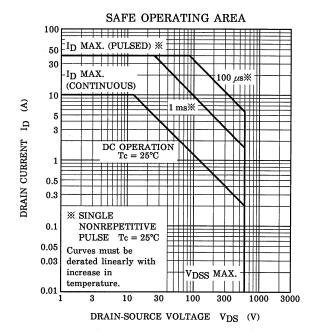


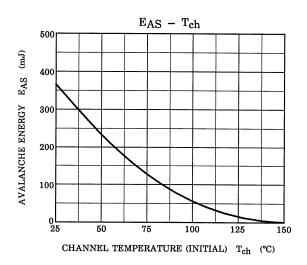


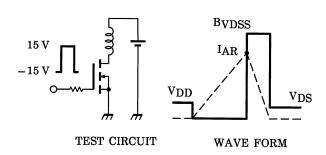












$$\begin{aligned} RG &= 25~\Omega \\ V_{DD} &= 90~V,~L = 6.36~mH \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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